



28 PA.

2827

U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICE

**SUPPLEMENTAL INFORMATION  
DISCLOSURE STATEMENT**

Docket Number:  
**52433/545**

Application Number  
**09/254,119**

Filing Date  
**April 16, 1999**

Examiner  
**Alonzo Chambliss**

Art Unit  
**2827**

Title  
**SEMICONDUCTOR DEVICE PROVIDED WITH  
LOW MELTING POINT METAL BUMPS**

Applicant(s)  
**K. TATSUMI et al.**

Address to:  
Commissioner for Patents  
Washington, D.C. 20231

I hereby certify that this correspondence is being deposited with  
the United States Postal Service as first class mail in an envelope  
addressed to: Commissioner for Patents, Washington, D.C. 20231  
on  
Date: **MARCH 5, 2003** Reg. No. 29, 182

Signature: **John J. Kelly, Jr.**  
John J. Kelly, Jr.

1. In accordance with the duty of disclosure under 37 C.F.R. § 1.56 and in conformance with the procedures of 37 C.F.R. §§ 1.97 and 1.98 and M.P.E.P. § 609, attorney(s) for Applicant(s) hereby bring the reference(s) listed on the attached modified PTO Form No. 1449 to the attention of the Examiner. It is respectfully requested that the information be expressly considered during the prosecution of this application, and that the reference(s) be made of record therein and appear among the "References Cited" on any patent to issue therefrom.
2. A copy of each patent, publication or other information listed on the modified PTO form 1449 is enclosed, except as otherwise indicated.
3. Pursuant to 37 C.F.R. § 1.97(c) and § 1.97(e), Applicants' attorney certifies that each item of information contained in the information disclosure statement was first cited in a communication dated December 5, 2002 from a foreign patent office in a counterpart foreign (European) patent application not more than three months prior to the filing of information disclosure statement.
4. While no fee is believed to be due, the Commissioner is authorized (as appropriate or necessary) to charge any additional fees or credit any overpayment to Deposit Account No. 11-0600. A duplicate copy of this paper is enclosed for that purpose.

Dated: **MARCH 5, 2003**

By: **John J. Kelly, Jr.**  
John J. Kelly, Jr. (Reg. No. 29,182)

KENYON & KENYON  
One Broadway  
New York, N.Y. 10004  
(212) 425-7200 (telephone)  
(212) 425-5288 (facsimile)

**CUSTOMER NO. 26646**

**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**ATTY. DOCKET NO.  
52433/545U.S. SERIAL NO.  
09/254,119APPLICANT  
K. TATSUMI et al.FILING DATE  
April 16, 1999GROUP  
2827**U. S. PATENT DOCUMENTS**

EXAMINER INITIAL	PATENT NUMBER	PATENT DATE	NAME	CLASS	SUBCLASS	FILING DATE*

**FOREIGN PATENT DOCUMENTS**

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

**OTHER DOCUMENTS**

EXAMINER INITIAL		AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.
		"Micro-ball Bump Technology For Fine-pitch Interconnections", Shimokawa K; Tatsumi K; Hashino E; Ohzeki Y; Konda M; Kawakami Y; Conference Proceedings Article 1 <sup>st</sup> 1997 IEMT/IMC Symposium (IEEE Cat. No. 97CH36059), Proceedings of 1997 First International Electronic Manufacturing Technology (IEMT) IMC Symposium, Tokyo, Japan, 16-18 April 1997; ISBN 0-7803-4235-6, pages 105-109.

EXAMINER	DATE CONSIDERED
EXAMINER: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	